

the heat sink plate has concavo-convex portions formed on an exposed surface thereof and is disposed [so as to be opposed] to make direct contact with a main surface on which semiconductor elements of the semiconductor chip are formed; and

the heat sink plate is so formed that the convex portions do not protrude from the surface of the sealing member to the outside.

3. (Amended) [The semiconductor device according to claim 1] A  
semiconductor device comprising:

a substrate;

a semiconductor chip mounted on the substrate;

external electrodes provided on the back of the substrate for connecting electrodes of the semiconductor chip to the outside;

a sealing member for encapsulating the semiconductor chip on the substrate; and

a heat sink plate fixed by the sealing member, wherein

the heat sink plate has a concavo-convex portions formed on an exposed surface thereof and is disposed so as to be opposed to a main surface on which semiconductor elements of the semiconductor chip are formed and so as to adjoin the main surface with a thin sealing member placed on the main surface [of the semiconductor chip] being interposed therebetween; and

the heat sink plate is formed so that the convex portions do not protrude from the surface of the sealing member to the outside.

Please cancel claim 5.